



Company Contact: Justin Moll, Pixus Technologies Justin.moll@pixustechnologies.com 519-885-5775

Pixus Releases Conduction-Cooled Version of OpenVPX Chassis Manager

Waterloo, Ontario — Jan 25, 2021 – Pixus Technologies, a provider of embedded computing and enclosure solutions, now offers a conduction-cooled model for their 3U OpenVPX Chassis Manager.

Compliant to the VITA 46.11 specification for system management and to VITA 48.2 for mechanical design, the Tier 2 Pixus OpenVPX Chassis Manager monitors at least 6 temperature sensors and 10 fans with custom options available. There is fan PWM/Tach control, along with 16 digital inputs and outputs. A Level-2 unmanaged 3- port Ethernet hub is also optional. The standard panel interface has RS-232, RJ-45, USB and LEDs.

The Pixus SHM200 features a Web interface to remotely query the system and the user can import images of their boards. By clicking on the image for each slot, the user can drill down to the monitored status of the module.

Pixus offers OpenVPX backplanes, chassis platforms, and specialty products. The company also provides enclosure solutions in MicroTCA, cPCI Serial, AdvancedTCA, as well as instrumentation case formats.

About Pixus Technologies

Leveraging over 20 years of innovative standard products, the Pixus team is comprised of industry experts in electronics packaging. Founded in 2009 by senior management from Kaparel Corporation, a Rittal company, Pixus Technologies' embedded backplanes and systems are focused primarily on ATCA, OpenVPX, MicroTCA, and custom designs. Pixus also has an extensive offering of VME-based and cPCI-based solutions. In May 2011, Pixus Technologies became the sole authorized North and South American supplier of the electronic packaging products previously offered by Kaparel Corporation and Rittal.